## Monday 5 October

- 9:30 – 12:30: 11th European FIB Users Group Meeting, EFUG workshop
- 14:00 – 15:40: Tutorial “Thermal Management of power electronics systems”
- 15:40 – 16:00: Coffee break
- 16:00 – 18:00: Workshop "Reliability on harsh environment"
- 14:00 – 18:00: 11th European FIB Users Group Meeting, EFUG workshop

## Tuesday 6 October

- 8:50 – 10:30: Tutorial “MEMS Reliability: Where are we now?”
- 10:30 – 10:50: Coffee break
- 10:50 – 12:30: Tutorial "ESD testing of devices, ICs and systems”
- 10:50 – 12:30: Tutorial “Physical Mechanisms and Modeling of the Bias Temperature Instability"
- 12:30 – 14:00: Lunch
- 14:00 – 14:20: Conf. Opening
- 14:20 – 15:00: **Invited** “Process dependence of BTI reliability in advanced HK MG stack
- 15:00: Best Paper IRPS
- Best Paper IPFA
- 15:40 – 16:00: Coffee break
- 16:00 – 17:40: Session A : Quality and Reliability Techniques for Devices and Systems
- 17:40 – 18:00: Presentation of Exhibitors
- 18:00: Author's corner

## Wednesday 7 October

- 8:30 – 10:30: Session F : Extreme environments: Power devices reliability
  **Invited** “Reliability challenges of automotive power electronics”
- 10:30 – 10:50: Coffee break
- 10:50 – 12:30: Session F : Extreme environments: Power devices, automotive and spatial electronics reliability
- 10:50 – 12:30: Session C1: Electron and Optical Beam Testing (EOBT)
  **Invited** “Laser THz emission microscope as a novel tool for LSI failure analysis”
- 12:30 – 12:50: Author's corner
- 12:50 – 14:00: Lunch
- 14:00 – 15:40: Session E : Packaging, Passive Components and MEMS
  **Invited** “Quasi hermetic packaging for new generation of spaceborn microwave equipment”
- 15:40 – 16:00: Author's corner
- 16:00: Coffee break
- 14:00: Sessions C1 C2 Advanced Techniques for failure analysis and Case studies
  **Invited** “Physical Analysis, Trimming and Editing of Nanoscale IC Function with Backside FIB Processing”
- Author's corner
- Coffee break
- 16:40 – 18:00: Poster session
- 18:00 – 19:30: Workshop EUFANET

## Thursday 8 October

- 8:30 – 10:30: Session B2: Failure Mechanisms in Si technologies and Nanoelectronics (Low K materials, Cu interconnects, ESD ...)
  **Invited** “Do ESD fails in systems correlate with IC ESD robustness?”
- 10:30 – 10:50: Author's corner
- 10:50 – 11:10: Coffee break
- 11:10 – 12:50: Session E : Packaging, Passive Components and MEMS
  **Invited** “Reliability, Prognostics and Risk Assessment Modelling for Electronics Packaging”
- 12:50 – 13:10: Author's corner
- 13:10 – 14:20: Lunch
- 14:20 – 16:20: Session B1: Failure Mechanisms in Si technologies and Nanoelectronics : NBTI
  **Invited** : Best Paper RCJ
- 16:20 – 16:40: Coffee break
- 16:40: Session B1: Failure Mechanisms in Si technologies and Nanoelectronics : Oxide Reliability
- 18:00: Author's corner

## Friday 9 October

- 8:30 – 10:10: Session D: Failure Mechanisms in Microwave and High Bandgap Devices
  **Invited** “GaN HEMT Reliability”
- 10:10 – 10:30: Author's corner
- LOTUS Workshop
- 10:30 – 10:50: Coffee break
- 10:50 – 12:30: Session D: Failure Mechanisms in Photonic Devices
  **Invited** “Towards Reliable Thin-Film Encapsulation of Organic Electronic Devices”
- 10:50 – 12:30: LOTUS Workshop
- 12:30 – 13:00: BPA And closing